

## Product Description

EVSF300 2.0 W/mK silicone-based thermal pads are used for filling the two contact surfaces. They are ultra-soft and have good resilience, so effectively exclude air from the contact interface. The products are naturally tacky, can be die-cut into various shapes, easy to operate.

## Product Illustration



## Features and Benefits

- High Thermal Conductivity
- Excellent Flame Retardant
- Good Flexibility and Resilience

## Applications

- CPU/GPU Chips
- Control Boards
- Memory/Graphics Memory Particles

(Standard sheet size 200mm x 300mm. Material may be cut per customer drawing.)

Properties	Unit	Value	Test Method
Color	-	Gray	Visual
Thermal Conductivity	W/mK	2.0	ASTM D5470
Thermal Impedance (1mm, @30psi)	°C*in <sup>2</sup> /W	0.70	ASTM D5470
Thickness	mm	0.3 – 10.0	ASTM D374
Tensile Strength	psi	40	ASTM D412
Standard Hardness	Shore 00	40/60	ASTM D2240
Elongation	%	50	ASTM D412
Density	g/cm <sup>3</sup>	2.1	ASTM D792
Dielectric Strength (@AC)	kV/mm	> 8	ASTM D149
Operating Temp.	°C	-50 - 200	-
Flame Rating	-	V-0	UL94
RoHS	-	PASS	IEC 62321
Halogen	-	PASS	EN 14582
REACH	-	PASS	EN 14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

**Product Specifications:** According to Customers' Requirements

**Storage & Transportation:** Store in a well-ventilated, cool, and dry place, away from open flames. This product is non-toxic and should be stored and transported as a non-hazardous material.

**Packaging:** Customized packaging according to customer requirements.

**Shelf Life:** 24 months